

# 2017 INTERNATIONAL MICROWAVE SYMPOSIUM

4 – 9 JUNE 2017 HONOLULU, HAWAII

## CALL FOR PRESENTATIONS

### COME JOIN US IN HONOLULU AND ENJOY THE FLAGSHIP MICROWAVE THEORY AND TECHNIQUES SOCIETY (MTT-S) CONFERENCE IN THE ALOHA STATE OF HAWAII

The IEEE Microwave Theory and Techniques Society's 2017 International Microwave Symposium (IMS2017) will be held 4 - 9 June 2017 at the Hawai'i Convention Center in Honolulu, Hawai'i as the centerpiece of Microwave Week 2017. New for IMS2017 are Exhibitor Workshops that provide IMS exhibitors a unique opportunity to present in-depth technical topics, via two-hour sessions, in a meeting room off the exhibit floor. Microwave Application Seminars (MicroApps) return as a forum on the exhibition floor for IMS exhibitors to present the technology and special capabilities behind their commercial products. Both presentation formats are open to all conference and exhibit attendees – Exhibitor Workshops require a nominal fee, and MicroApps are free of charge. Please visit [www.ims2017.org](http://www.ims2017.org) for full details.

	Exhibitor Workshops	MicroApps
<b>Presentation Topics</b>	State-of-the-Art Products and Processes of Interest to the Microwave Community	
<b>Presentation Length</b>	Two Hours	10 - 15 Minutes
<b>Presentation Format and Location</b>	Workshop in Classroom-Style Meeting Room off the Exhibit Floor	Seminar in MicroApps Theater on the Exhibit Floor
<b>Publication Format</b>	IMS2017 Exhibitor Workshop Digest	IMS2017 MicroApps Virtual Proceedings
<b>Cost to IMS Exhibitor</b>	Free (Limited to Paid IMS2017 Exhibitors)	Free (Limited to Paid IMS2017 Exhibitors)
<b>Cost to IMS Registrant</b>	Nominal Fee	Free

IMS2017 exhibitors are invited to submit abstracts for Exhibitor Workshops and MicroApps technical papers describing state-of-the-art products and processes of interest to the microwave community. Abstract submission files will be considered for oral presentation, as well as electronic distribution, to IMS attendees.

**Submissions for Exhibitor Workshops and MicroApps presentations are limited to paid exhibitors registered for IMS2017.**

**Electronic Submission:** Exhibitor Workshop submissions must be submitted via email to [ims2017.exhibitorworkshops@gmail.com](mailto:ims2017.exhibitorworkshops@gmail.com). MicroApps technical papers must be submitted via email to [ims2017.microapps@gmail.com](mailto:ims2017.microapps@gmail.com).

<b>Electronic Submission Deadlines:</b>	Exhibitor Workshops	MicroApps
Abstract for Review:	5 December 2016	5 December 2016
Final Manuscripts:	Not Applicable	17 March 2017
Final Presentation Submission:	22 May 2017	22 May 2017
All submissions must be made via email:	<a href="mailto:ims2017.exhibitorworkshops@gmail.com">ims2017.exhibitorworkshops@gmail.com</a>	<a href="mailto:ims2017.microapps@gmail.com">ims2017.microapps@gmail.com</a>

**All submissions must be in PDF form – hard copies not accepted.**



#### Symposium Chairs

W. Shiroma (General Chair), K. Miyashiro (Co-Chair),  
V. Lubecke (Vice Chair)

#### Technical Program

O. Boric-Lubecke (Co-Chair), R. Miyamoto (Co-Chair),  
T. Itoh (Senior Advisor), A. Crahan (Administrator)

#### Electronic Paper Management

J. Hacker, M. DeLisio, S. Owens

#### Workshops and Short Courses

C. Hang, Y.-C. Shih, K. Leong, B. Wu, L. Rabieirad,  
C. Song, L. Dunleavy, K. Hall, S. Kumar

#### Panel, Rump, Focus, and Special Sessions

C. Jackson, R. Kagiwada, A. Oki, T. LaRocca,  
Y. E. Wang, C. Rodenbeck

#### Interactive Forum

D. Bibb, G. C. Huang, R. Perron

#### Plenary Session and 5G Summit

V. Lubecke, D. Choudhury, T. LaRocca,  
J. Laskar, D. Zuckerman

#### Technical Program Competitions

R. Gough, E. Yavari, X. Gao, A. Rahman, P. Orel,  
S. Rosenau, J. Bandler, E. Kiley

#### TPC at Large

Z. Bardai, J. Lin, H. Okazaki

#### Publicity, Promotions, and Publications

M. Watanabe, K. Kogasaka, J. Roque, A. Scacchitti

#### Website and Program Book

C. Brough, D. Goshi, M. Moorefield

#### Social Media

K. Cho, J. Hofer, M. Visitacion, J. Warner

#### Microwave Magazine

I. Mostafanezhad, A. Singh

#### Local Arrangements / Operations

J. M. Akagi, A. Noveloso, Z. Bardai,  
M. Tamamoto, J. T. Akagi, B. Lei, G. Uyeda,  
A. Ohta, A. Combs

#### Finance and Registration

D. Goshi, K. Leong, T. Fujishige, R. Alongi,  
N. Jordan

#### Student Volunteer Coordination

A. Morishita, J. Dang, T. Chun

#### Focus Groups

R. Pang, R. Iwami, B. Lei

#### Young Professionals

A. Zamora, K. Lu, W. Tonaki, T. Sharma,  
K. Allen

#### Women in Microwaves

C. Kitamura, J. Nakatsu, A. Pham,  
S. Yamada

#### STEM and Project Connect

C. Ishii, K. Matthews, D. Ah Yo, R. Mukai,  
A. Noveloso, K. Lau, G. Zhang

#### MicroApps and Exhibitor Workshops

J. Guzman-Vazquez, G. Uekawa, J. Weiler,  
B. Wu

#### Historical and University Exhibits

A. Combs, J. Hausner, J. Navarro, K. Sarabia

#### Global Ambassadors

K. Wu, D. Zimmerman

#### Conference and Exhibition Management

E. Vega, L. Wood, S. Horn, D. Waldron

#### Senior Advisors

T. Weller, S. Kanamaluru



**A submission must include:**

1. Author information: name(s), title(s), company affiliation, telephone number, and email address.
2. A 100 - 300 word abstract (in English) in PDF format. No zip files. Describe the product or process, its importance to the microwave community and how it advances the state of the art in an application.
3. A statement using company letterhead authorizing IMS2017 to print your abstract and to publish your technical presentation in the IMS2017 Exhibitor Workshop Digest or IMS2017 MicroApps Virtual Proceedings and other official IMS2017 electronic publications.

The decision to accept a seminar or workshop for presentation is based on this summary, its novelty, and overall number of submissions received, as well as confirmation that your company is a registered and paid exhibitor at IMS2017.

**Exhibitor Workshop Selection Criteria:** Exhibitors are invited to submit an abstract detailing a workshop presentation. All submissions must be in English, and should outline the two-hour session, including products, processes, and techniques to be covered. Novel or noteworthy state-of-the-art components, new technologies, manufacturing and design techniques incorporating the exhibitor’s products and technologies should also be included. All submissions will be reviewed by the Exhibitor Workshop Committee. Workshops are open to all IMS registrants for a nominal fee and should appeal to the exhibit attendees. The selection criteria include: relevance and interest to MTT-S members and IMS2017 exhibition attendees, cross section and novelty of topics, and equitable representation of exhibitors.

**MicroApps Selection Criteria:** Exhibitors are invited to submit an abstract detailing an applications presentation. All submissions must be in English, and may cover new products, noteworthy state-of-the-art components, new technologies, and manufacturing and design techniques incorporating the exhibitor’s products and technologies. All submissions will be reviewed by the MicroApps Committee. Papers are open to all IMS registrants and should appeal to the exhibit attendees. The selection criteria include: relevance and interest to MTT-S members and IMS2017 exhibition attendees, novelty of topic (avoidance of duplicate material from prior years), and equitable representation of exhibitors.

**Exhibitor Workshop Presentation Format:** Presentation formats are flexible. AV equipment including projector & screen with audio inputs will be available. Workshops take place in designated meeting rooms on Level 3 of the Hawaii Convention Center. Seating will be arranged in classroom style. Workshops are two-hours in length. Presentation schedule will be set by the Exhibitor Workshop Committee. The file for the electronic media should not exceed 100MB. Additional materials may be distributed to participants at the time of the Workshop. Presentations may be made using either the session PC or the presenter’s laptop. Presentations for inclusion in the digest must be submitted by 22 May 2017. Please visit [www.ims2017.org](http://www.ims2017.org) for full details.

**MicroApps Presentation Format:** PowerPoint presentations (or their equivalent PDF output) are required. Embedded animations/videos are encouraged. The presentations are made in the MicroApps Theater located on the exhibit floor. Acoustics will be employed that permit everyone inside the theater to hear the presentation and exhibitors outside to conduct normal business. Your company will be given the opportunity to invite people to hear your presentation using a free IMS2017 “Exhibition Only” pass. For an additional fee, presentations will be recorded and original files will be provided to your company following IMS. Seminar presentations are typically 10–15 minutes in length. Time allocations for each presentation will be set by the review committee. Allotted presentation time may be reduced for multiple submissions from the same exhibitor. The file for the electronic media should not exceed 100 MB. The electronic media is offered free of charge to all MicroApps attendees. Presentations will be made using the session PC and are due by 22 May 2017. Please visit [www.ims2017.org](http://www.ims2017.org) for full details.

**Notification:** Exhibitor Workshop and MicroApps authors will be notified, by email, of the evaluation results in February 2017.

**MicroApps and Exhibitor Workshops Suggested Areas of Interest (other topics will also be considered)**

The objective of Exhibitor Workshops and MicroApps are to reach the diverse audience of young engineers and technicians, as well as industry veterans, from around the world. Workshops, tutorials and application notes on basic techniques and fundamental knowledge are encouraged. Exhibitor Workshops and MicroApps are intended to communicate practical knowledge; marketing, sales, and purely theoretical presentations are strongly discouraged. Presenters are encouraged to invite attendees to visit their exhibit for further discussion following their Exhibitor Workshop or MicroApps presentations.

**CAE/CAD and Modeling Products and Techniques**

- Design for testability
- Design for manufacturability
- Device or system design

**Mechanical and Passive Components**

- Transmission lines
- Filters and multiplexers
- Ferrite and acoustic components
- Conventional passive devices
- MEMS components and technologies

**Packaging and Interconnects**

**Manufacturing Processes**

**Active Components**

- Digital and mixed signal circuits
- Oscillators and frequency sources
- RF power devices and amplifiers
- Low noise receivers and components
- Monolithic microwave integrated circuits (MMIC)
- New semiconductor technologies
- Optoelectronics for microwave / millimeter-wave applications
- Superconducting components and technology
- Switches, phase shifters, limiters, mixers, frequency multipliers
- Terahertz devices

**Sub-Assemblies**

- Hybrids and modules
- Microwave systems
- Wireless and cellular communications
- Broadband communication
- Sensors and sensor systems
- RFID
- 4G and 5G

**Calibration, Instrumentation and Test Measurement Techniques**

- Novel measurement techniques
- Assembly test techniques
- Basic RF and microwave “how-to” test procedures
- Wafer and die RF probe
- Extreme environments evaluation

**See [www.ims2017.org](http://www.ims2017.org) for the latest available information**